

13. (Twice amended) The processor in claim 12, wherein said at least one dispenser further comprises:

- a first dispenser on a first side of said wafer accommodation area; and
- a second dispenser on a second side of said wafer accommodation area.

Cont.
C1
14. (Twice amended) A bead remover for a wafer, comprising:

- a negative pressure mechanism configured to be spaced from a bead on said wafer while operating upon said bead; and
 - a dispensing mechanism aligned with said negative pressure mechanism, wherein said dispensing mechanism is configured to deliver a chemical that dissolves said bead.
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C2
15. (Once amended) A bead remover for a wafer, comprising:

- a negative pressure mechanism configured to be spaced from a bead on said wafer while operating upon said bead; and
 - a solvent-dispensing mechanism aligned with said negative pressure mechanism, wherein said solvent-dispensing mechanism is concentric to said negative pressure mechanism.
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C3
17. (Twice amended) An edge bead remover configured to service a spinning wafer, comprising:

- a nozzle configured to apply an edge bead-dissolving substance to an edge of said wafer;
 - and
 - a vacuum mechanism enveloping said nozzle and offset from an edge bead during application of said substance to said edge.
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C4
18. (Once amended) The edge bead remover of claim 17, wherein said vacuum mechanism is configured to remove said substance from said edge.

19. (Once amended) An edge bead remover configured to service a spinning wafer, comprising:
a nozzle configured to apply an edge bead-dissolving substance to an edge of said wafer;
and

a vacuum mechanism enveloping said nozzle and offset from said edge during application
of said substance to said edge, wherein said vacuum mechanism is configured to
remove said substance from said edge, and wherein said vacuum mechanism
envelopes said edge.

Cont.
C4

20. (Twice amended) A material removal system for a wafer, comprising:

a negative pressure device defining a vacuum area intersecting said wafer while said
device is in an operational position; and

a solvent dispenser intersecting said vacuum area and aligned with an edge of said wafer
while said device is in said operational position.

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C5

21. (Twice amended) The material removal system of claim 20, wherein said negative pressure
device is distal from said wafer while said device is in said operational position.

24. (Twice amended) A chemical dispensing system for a workpiece, comprising:

a negative pressure device defining a portal disposed toward and spaced from all surfaces
of said workpiece while acting upon said workpiece; and

a first dispenser within said negative pressure device and disposed toward at least one
surface of said workpiece while dispensing a chemical that dissolves a material on
said workpiece.

C6

26. (Once amended) A chemical dispensing system for a workpiece, comprising:

a negative pressure device defining a portal disposed toward and spaced from all surfaces of said workpiece while acting upon said workpiece, wherein said portal is spaced around an edge of said workpiece;

CM a first solvent dispenser within said negative pressure device and disposed toward at least one surface of said workpiece while acting upon said workpiece; and

a second solvent dispenser within said negative pressure device, disposed toward said edge, and opposing said first solvent dispenser.

28. (Twice amended) A chemical remover for a substrate, comprising:

CG a nozzle directed toward said substrate during a dispensation mode and configured to couple to a source of a chemical that can dissolve a material on said substrate; and

a vacuum device spaced from said material and directed toward said nozzle during said dispensation mode.

29. (Twice amended) A profiler for a wafer, comprising:

a dispenser perpendicular to said wafer during a dissolution process; and

a vacuumer surrounding at least a portion of said dispenser and separate from an outermost surface of said wafer during said dissolution process.

C9 30. (Once amended) The profiler in claim 29, wherein said dispenser further comprises a location wherein solvent exits said dispenser; and wherein said vacuumer surrounds said location.

31. (Twice amended) A profiler for a wafer, comprising:

a dispenser perpendicular to said wafer during a dissolution process and comprising a location wherein solvent exits said dispenser;

a vacuumer surrounding at least a portion of said dispenser and separate from said wafer during said dissolution process, wherein said vacuumer surrounds said location; and

an additional dispenser perpendicular to said wafer; wherein said vacuumer surrounds at least a portion of said additional dispenser.

32. (Twice amended) The profiler in claim 31, wherein said dispenser is disposed toward a top side of said wafer.

33. (Twice amended) The profiler in claim 32, wherein said additional dispenser is disposed toward a bottom side of said wafer.

A marked-up version of these claims appears in Appendix I.

REMARKS

Claims 12-33 are pending.

Claims 12-33 are rejected.

Claims 12-15, 17-21, 24, 26, and 28-33 are amended.

The Examiner rejected various groups of claims citing Japanese Patent 8-5825 by Honda, Japanese Patent 56-73579 by Uchida, or a combination of both. Applicant addresses each basis for rejection separately below.

I. Rejection of claims under 35 U.S.C. §102(a)

The Examiner rejected claims 12-14 and 17-33 as being anticipated by Honda. Applicant contends that the current state of the claims contain limitations that distinguish those claims from the matters disclosed in Honda.